


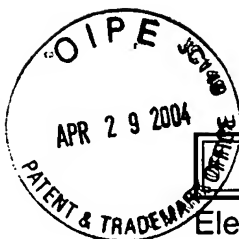


Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 60088
Application ID: 10643638 
Title of Invention: BOILING TEMPERATURE DESIGN
IN PUMPED MICROCHANNEL
COOLING LOOPS
First Named Inventor: Peng Zhou
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-08-18
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Statement
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Confirmation number: 4432
Attorney Docket Number: NONE


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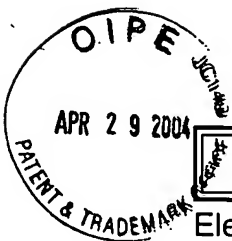
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**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	BOILING TEMPERATURE DESIGN IN PUMPED MICROCHANNEL COOLING LOOPS									
Application Number: 10/643638 										
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Attorney Docket Number:										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>COOL01500D-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	COOL01500D-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	COOL01500D-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

BOILING TEMPERATURE DESIGN IN PUMPED
MICROCHANNEL COOLING LOOPS

Application Number: 10/643638



Confirmation Number: 4432

First Named Applicant: Peng Zhou

Attorney Docket Number:

Search string: (6591625 or 6632655 or 20010016985 or
20010024820 or 20010044155 or 20010045270
or 20010046703 or 20010055714 or
20020011330 or 20020134543).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6591625	2003-07-15	Simon	B1		
	2	6632655	2003-10-14	Mehta et al.	B1		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010016985	2003-08-30	Insley et al.	A1		
	2	20010024820	2001-09-27	Mastromatteo et al.	A1		
	3	20010044155	2001-11-22	Paul et al.	A1		
	4	20010045270	2001-11-29	Bhatti et al.	A1		
	5	20010046703	2001-11-29	Burns et al.	A1		
	6	20010055714	2001-12-27	Cettour-Rose et al.	A1		
	7	20020011330	2002-01-31	Insley et al.	A1		
	8	20020134543	2002-09-26	Estes et al.	A1		

Signature

Examiner Name	Date